

**PACKAGED INTEGRATED CIRCUIT PROVIDING
TRACE ACCESS TO HIGH-SPEED LEADS**

Abstract of the Disclosure

A packaged integrated circuit for installation on a printed wiring board (PWB) or other type
5 of circuit mounting structure, that allows for the routing of high-speed signals out from high-speed
leads on an underside of the packaged integrated circuit. The packaged integrated circuit comprises
a die and a package body formed from encapsulant that at least partially encloses the die. A
leadframe is also connected to the die and partially enclosed in the package body. Leads extend out
from the package body and a subset of these leads are separated by a lead-to-lead pitch. At least two
10 adjacent leads of the leadframe are separated by a space larger than the pitch. An additional lead is
also connected to the die and disposed on an underside of the package. The additional lead is
connectable to a circuit mounting structure trace passing between the adjacent leads separated by the
space larger than the pitch.